

# TLV62090 采用 DCS-Control™ 拓扑的 3A 高效同步降压转换器

## 1 特性

- 2.5V 至 5.5V 输入电压范围
- DCS-Control™
- 效率最高可达 98%
- 省电模式
- 20 $\mu$ A 运行静态电流
- 针对最低压降的 100% 占空比
- 1.4MHz 典型开关频率
- 0.8V 至  $V_{IN}$  的可调输出电压
- 输出放电功能
- 可调节软启动
- 断续短路保护
- 输出电压跟踪
- 与 [TPS62090](#)、[TLV62095](#) 和 [TPS62095](#) 引脚至引脚兼容
- 有关改进的功能集，请参见 [TPS62090](#)
- 使用 TLV62090 并借助 [WEBENCH® Power Designer](#) 创建定制设计方案

## 2 应用范围

- 分布式电源
- 笔记本、上网本
- 硬盘驱动器 (HDD)
- 固态硬盘 (SSD)
- 处理器电源
- 电池供电类应用

## 3 说明

TLV62090 器件是一款高频同步降压转换器，经优化具有小解决方案尺寸和高效率两大优点，非常适合电池供电类应用。为了最大限度地提高效率，该转换器以 1.4MHz 的标称开关频率在脉宽调制 (PWM) 模式下工作，并且会在轻负载电流条件下自动进入节能工作模式。在分布式电源和负载点稳压应用中，该器件允许对其他电压轨的电压进行跟踪，并且允许采用介于 10 $\mu$ F 至 150 $\mu$ F 范围内甚至更高的输出电容。通过使用 DCS-Control 拓扑，此器件可实现出色的负载静态性能以及精确的输出电压调节。

输出电压启动斜坡由软启动引脚控制，可由独立电源供电运行，也可在跟踪配置下运行。此外，还可以通过配置使能 (EN) 引脚和电源正常状态 (PG) 引脚实现电源排序。在节能模式下，该器件静态工作电流的典型值为 20 $\mu$ A。在整个负载电流范围内，自动进入省电模式并且以无缝方式保持高效。

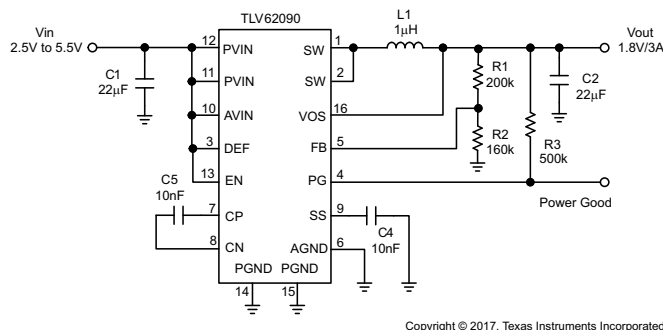
该器件采用 3mm x 3mm 16 引脚超薄四方扁平无引线 (VQFN) (RGT) 封装。

器件信息<sup>(1)</sup>

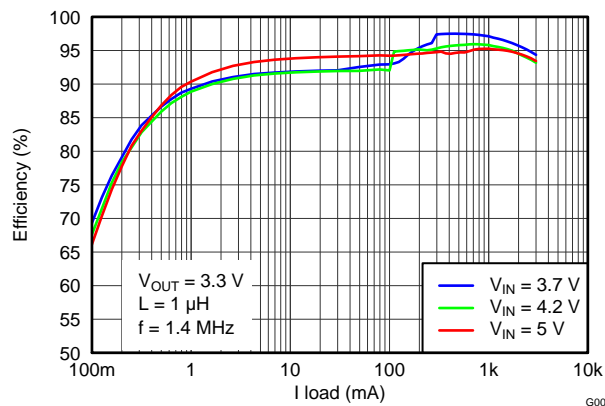
器件型号	封装	封装尺寸 (标称值)
TLV62090	VQFN (16)	3.00mm x 3.00mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。

典型应用电路原理图



效率与输出电流间的关系



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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision E (January 2016) to Revision F	Page
• 已添加特性：与 TPS62090、TLV62095 和 TPS62095 引脚至引脚兼容 .....	1
• 已添加特性：有关改进的功能集，请参见 TPS62090 .....	1
• 已添加 WEBENCH 信息至特性，详细设计流程和器件支持部分 .....	1
• Added SW (AC, less than 10 ns) to the <i>Absolute Maximum Rating</i> table .....	5
• 已添加 additional frequency curves to the <i>Typical Characteristics</i> section .....	7
• 已添加 表 1, Power Good Pin Logic .....	12

Changes from Revision D (September 2015) to Revision E	Page
• 已将标题由“3A 高效同步”更改至“3A 高效同步” .....	1
• 已将特性“转换器效率为 95%”更改至“效率最高可达 98%” .....	1
• 已将特性“两级短路保护”更改至“断续短路保护” .....	1
• 已将说明中的文本由“该器件在典型值为 20µA 的静态电流下工作”更改至“该器件静态工作电流的典型值为 20µA。” .....	1
• Deleted Note from the pinout drawing: <i>The exposed Thermal Pad is connected to AGND.</i> .....	4
• Changed the <i>Pin Functions</i> table I/O column .....	4
• Changed the <i>Pin Functions</i> table Description column for pins FB, EN, and Thermal Pad .....	4
• Added pins CN and CP to the Voltage range in <i>Absolute Maximum Ratings</i> <sup>(1)</sup> .....	5
• Deleted "Continuous total power dissipation" from <i>Absolute Maximum Ratings</i> <sup>(1)</sup> .....	5
• Deleted Note 1 from <i>Recommended Operating Conditions</i> .....	5
• Added EN = Low to the Description of R <sub>PD</sub> in <i>Electrical Characteristics</i> table .....	6
• Deleted I <sub>PG</sub> from the <i>Electrical Characteristics</i> table .....	6
• Changed L <sub>IMF</sub> to I <sub>LIMF</sub> for High side FET switch current limit in the <i>Electrical Characteristics</i> table .....	6
• Changed V <sub>s</sub> to V <sub>OUT</sub> for Output voltage range in the <i>Electrical Characteristics</i> table .....	6
• Changed 图 1 through 图 2 .....	7
• Added Note 1 to the <i>Functional Block Diagram</i> .....	9
• Changed "Softstart (SS) and Output Capacitor during Startup" To: <a href="#">Softstart (SS) and Hiccup Current Limit During</a> .....	

Startup .....	10
• Changed text From: "start-up especially for larger output capacitors >22 μF." To: "start-up especially for larger output capacitors." in <i>Softstart (SS) and Hiccup Current Limit During Startup</i> .....	10
• Rewrite the description in <i>Voltage Tracking (SS)</i> .....	10
• Deleted text "in PFM mode and with a minimum quiescent current while" from <i>Power Save Mode Operation</i> .....	13
• Changed $V_{OUT(max)}$ to $V_{OUT}$ in <i>公式 4</i> .....	13
• Deleted text " $V_{OUT(max)}$ = nominal output voltage plus maximum output voltage tolerance" from <i>公式 4</i> .....	13
• Added Note to <i>Application and Implementation</i> .....	14
• Added 10 nF to the description of C4, C5 in <i>表 3</i> .....	15
• Updated the Isat/DCR (max) column of <i>表 5</i> .....	16
• Deleted text" The inductor needs to be rated for a saturation current as high as the typical switch current limit, of 4.6 A or according to <i>公式 5</i> and <i>公式 6</i> ." from <i>Inductor Selection</i> .....	16
• Changed <i>公式 5</i> and <i>公式 6</i> .....	16
• Changed the <i>Input and Output Capacitor Selection</i> section .....	16
• Changed <i>图 19</i> .....	18
• Changed <i>图 20</i> .....	18

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<b>Changes from Revision C (May 2014) to Revision D</b>	<b>Page</b>
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• Moved Storage temperature From: <i>ESD Ratings</i> To: <i>Absolute Maximum Ratings</i> <sup>(1)</sup> .....	5
• Changed table From: <i>Handling Ratings</i> To: <i>ESD Ratings</i> .....	5
• Added PWM mode, $T_J = 25^{\circ}C$ to Feedback voltage accuracy section of the <i>Electrical Characteristics</i> table .....	6

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<b>Changes from Revision B (April 2012) to Revision C</b>	<b>Page</b>
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• 已添加 <i>ESD</i> 额定值表, 特性 描述部分, 器件功能模式, 应用和实施部分, 电源相关建议部分, 布局部分, 器件和文档支持部分以及机械、封装和可订购信息部分。 .....	1
• Deleted text: "TPS62090 adjustable output version" from the Feedback voltage accuracy section of the <i>Electrical Characteristics</i> table .....	6
• Changed <i>图 1</i> From: Resistance ( $\Omega$ ) To: Resistance (m $\Omega$ ).....	7
• Added Application Curves to the Application Information section.....	18
• Deleted Typical applications from the Application Information section for: 1.8 V Adjustable Version, 1.5 V Adjustable Version, 1.2 V Adjustable Version and 1.05 V Adjustable Version .....	20

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<b>Changes from Revision A (March 2012) to Revision B</b>	<b>Page</b>
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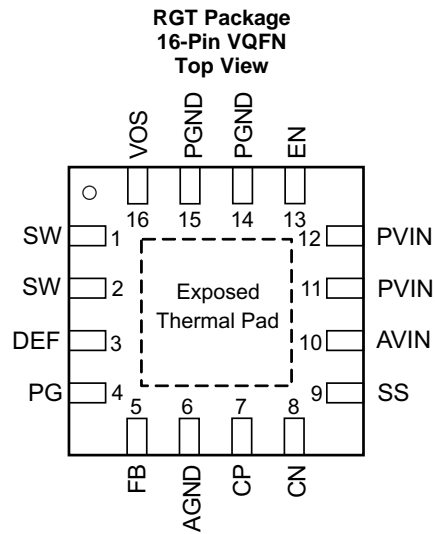
• Changed the Input voltage range MAX value From: 6V To 5.5V in <i>Electrical Characteristics</i> .....	6
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<b>Changes from Original (March 2012) to Revision A</b>	<b>Page</b>
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• Changed $V_{in}$ From: 2.5V to 6V To: 2.5V to 5.5V in <i>图 11</i> .....	14
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## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
SW	1, 2	I/O	Switch pin of the power stage.
DEF	3	I	This pin is used for internal logic and needs to be pulled high. This pin should not be left floating.
PG	4	O	Power good open drain output. This pin is high impedance if the output voltage is within regulation. This pin is pulled low if the output is below its nominal value. The pull up resistor can not be connected to any voltage higher than the input voltage of the device.
FB	5	I	Feedback pin of the device. Connect a resistor divider to set the output voltage.
AGND	6		Analog ground.
CP	7	I/O	Internal charge pump flying capacitor. Connect a 10 nF capacitor between CP and CN.
CN	8	I/O	Internal charge pump flying capacitor. Connect a 10 nF capacitor between CP and CN.
SS	9	I	Softstart control pin. A capacitor is connected to this pin and sets the softstart time. Leaving this pin floating sets the minimum start-up time.
AVIN	10	I	Bias supply input voltage pin.
PVIN	11,12	I	Power supply input voltage pin.
EN	13	I	Device enable. To enable the device this pin needs to be pulled high. Pulling this pin low disables the device. This pin has a pull down resistor of typically 400 k $\Omega$ , which is active when EN is low.
PGND	14,15		Power ground connection.
VOS	16	I	Output voltage sense pin. This pin needs to be connected to the output voltage.
Exposed Thermal Pad			The exposed thermal pad is connected to AGND. It must be soldered for mechanical reliability.

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

		VALUE		UNIT
		MIN	MAX	
Voltage range <sup>(2)</sup>	PVIN, AVIN, FB, SS, EN, DEF, VOS	- 0.3	7	V
	SW (DC), PG	- 0.3	V <sub>IN</sub> + 0.3	
	SW (AC, less than 10 ns) <sup>(3)</sup>	- 3.0	10	
	CN, CP	- 0.3	V <sub>IN</sub> + 7	
Power Good sink current	PG		1	mA
Operating junction temperature range, T <sub>J</sub>		- 40	150	°C
Storage temperature, T <sub>stg</sub>		- 65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) While switching

### 6.2 ESD Ratings

			MAX	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

		MIN	TYP	MAX	UNIT
V <sub>IN</sub>	Input voltage range V <sub>IN</sub>	2.5		5.5	V
T <sub>A</sub>	Operating ambient temperature	-40		85	°C
T <sub>J</sub>	Operating junction temperature	-40		125	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TLV62090	UNITS
		VQFN (16 PINS)	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	47	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	60	
R <sub>θJB</sub>	Junction-to-board thermal resistance	20	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.5	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	20	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	5.3	

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

 $V_{IN} = 3.6V$ ,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ , typical values are at  $T_A = 25^{\circ}C$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SUPPLY</b>						
$V_{IN}$	Input voltage range		2.5		5.5	V
$I_{QIN}$	Quiescent current	Not switching, FB = FB +5%, into PVIN and AVIN		20		$\mu A$
$I_{sd}$	Shutdown current	Into PVIN and AVIN		0.6	5	$\mu A$
$V_{UVLO}$	Undervoltage lockout threshold	$V_{IN}$ falling	2.1	2.2	2.3	V
	Undervoltage lockout hysteresis			200		mV
$T_{SD}$	Thermal shutdown	Temperature rising		150		$^{\circ}C$
	Thermal shutdown hysteresis			20		$^{\circ}C$
<b>CONTROL SIGNAL EN</b>						
$V_H$	High level input voltage	$V_{IN} = 2.5 V$ to $5.5 V$	1	0.65		V
$V_L$	Low level input voltage	$V_{IN} = 2.5 V$ to $5.5 V$		0.60	0.4	V
$I_{lkg}$	Input leakage current	EN = GND or $V_{IN}$		10	100	nA
$R_{PD}$	Pull down resistance	EN = Low		400		k $\Omega$
<b>SOFTSTART</b>						
$I_{SS}$	Softstart current		6.3	7.5	8.7	$\mu A$
<b>POWER GOOD</b>						
$V_{TH\_PG}$	Power good threshold	Output voltage rising	93%	95%	97%	
		Output voltage falling	88%	90%	92%	
$V_L$	Low level voltage	$I_{(sink)} = 1 mA$			0.4	V
$I_{lkg}$	Leakage current	$V_{PG} = 3.6 V$		10	100	nA
<b>POWER SWITCH</b>						
$R_{DS(on)}$	High side FET on-resistance	$I_{SW} = 500 mA$		50		m $\Omega$
	Low side FET on-resistance	$I_{SW} = 500 mA$		40		m $\Omega$
$I_{LIMF}$	High side FET switch current limit		3.7	4.6	5.5	A
$f_s$	Switching frequency	$I_{OUT} = 3 A$		1.4		MHz
<b>OUTPUT</b>						
$V_{OUT}$	Output voltage range		0.8		$V_{IN}$	V
$R_{od}$	Output discharge resistor	EN = GND, $V_{OUT} = 1.8 V$		200		$\Omega$
$V_{FB}$	Feedback regulation voltage	PWM Mode		0.8		V
$V_{FB}$	Feedback voltage accuracy $V_{IN} \geq V_{OUT} + 1 V$	$I_{OUT} = 1 A$ , PWM mode, $T_J = 25^{\circ}C$	-1%		+1%	
		$I_{OUT} = 1 A$ , PWM mode	-1.4%		+1.4%	
		$I_{OUT} = 0 mA$ , $V_{OUT} \geq 1.2 V$ , PFM mode <sup>(1)</sup>	-1.4%		+3%	
		$I_{OUT} = 0 mA$ , $V_{OUT} < 1.2 V$ , PFM mode <sup>(2)</sup>	-1.4%		+3.7%	
$I_{FB}$	Feedback input bias current	$V_{FB} = 0.8 V$		10	100	nA
	Line regulation	$V_{OUT} = 1.8 V$ , PWM operation		0.016		%/V
	Load regulation	$V_{OUT} = 1.8 V$ , PWM operation		0.04		%/A

(1) Conditions: L = 1  $\mu H$ ,  $C_{OUT} = 22 \mu F$ . For more information, see the [Power Save Mode Operation](#) section of this data sheet.

(2) For output voltages < 1.2 V, use a 2 x 22  $\mu F$  output capacitance to achieve +3% output voltage accuracy in PFM mode.

## 6.6 Typical Characteristics

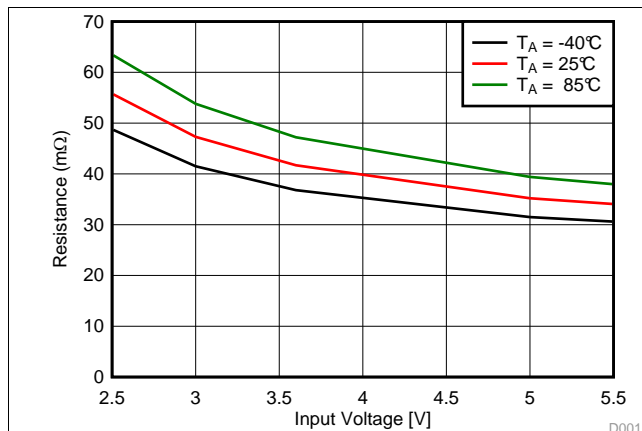


图 1. High Side FET On-Resistance vs Input Voltage

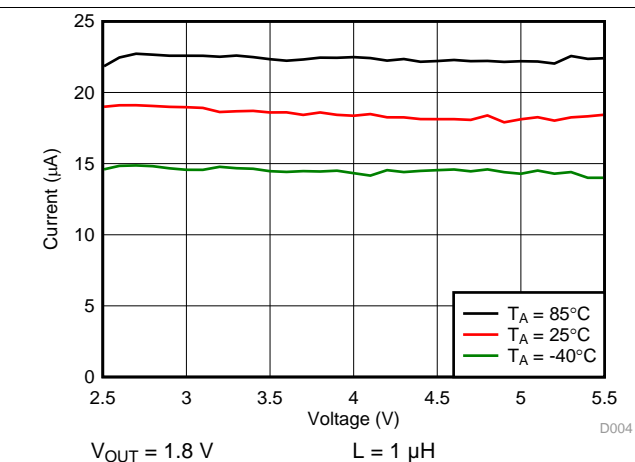


图 2. Quiescent Current vs Input Voltage

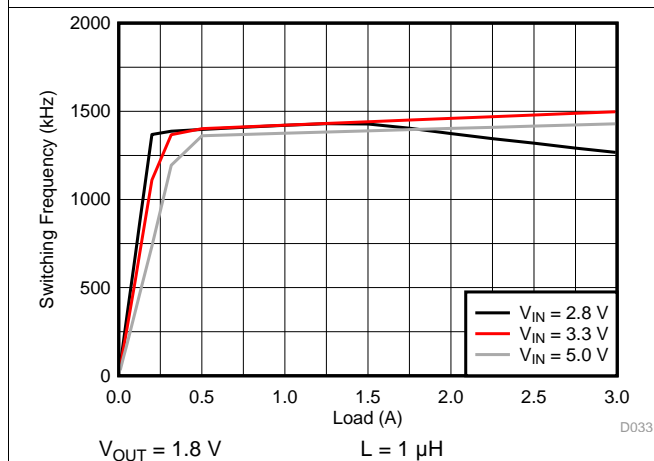


图 3. Switching Frequency vs Load Current

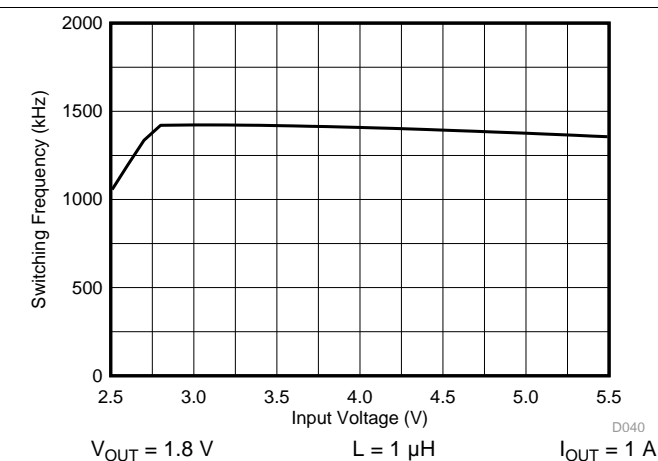


图 4. Switching Frequency vs Input Voltage

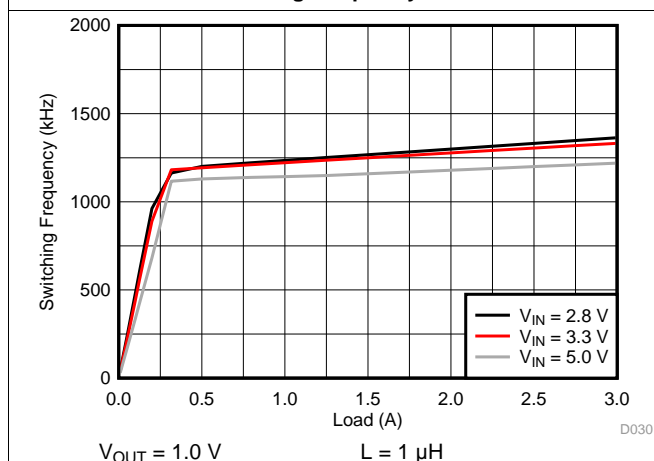


图 5. Switching Frequency vs Load Current

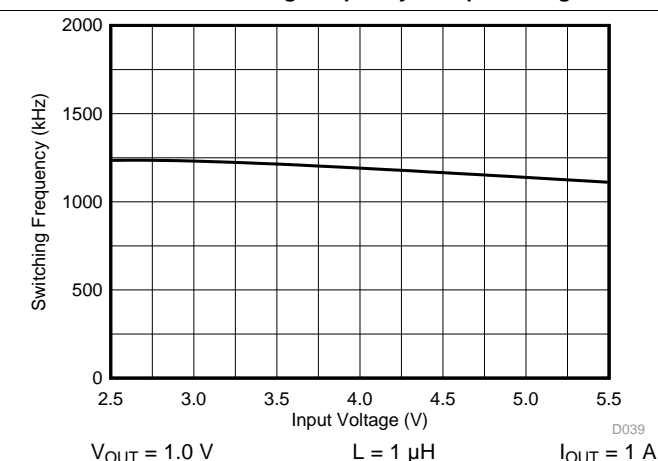
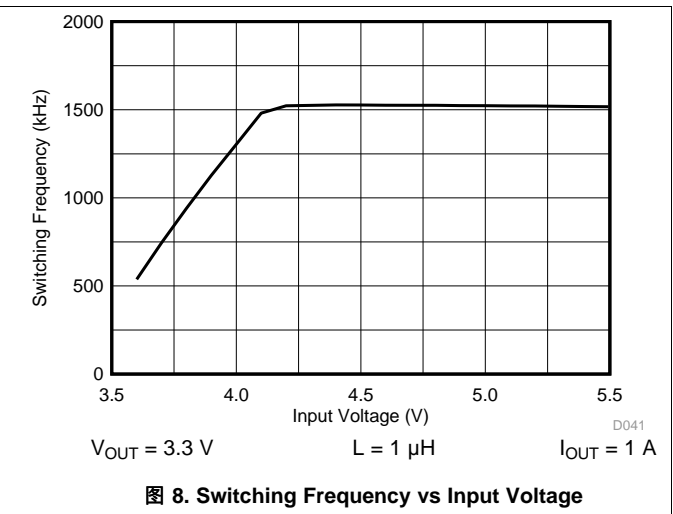
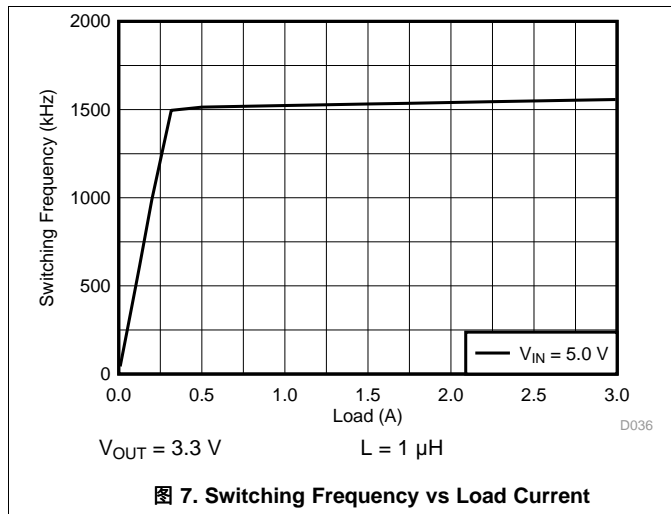


图 6. Switching Frequency vs Input Voltage

Typical Characteristics (接下页)





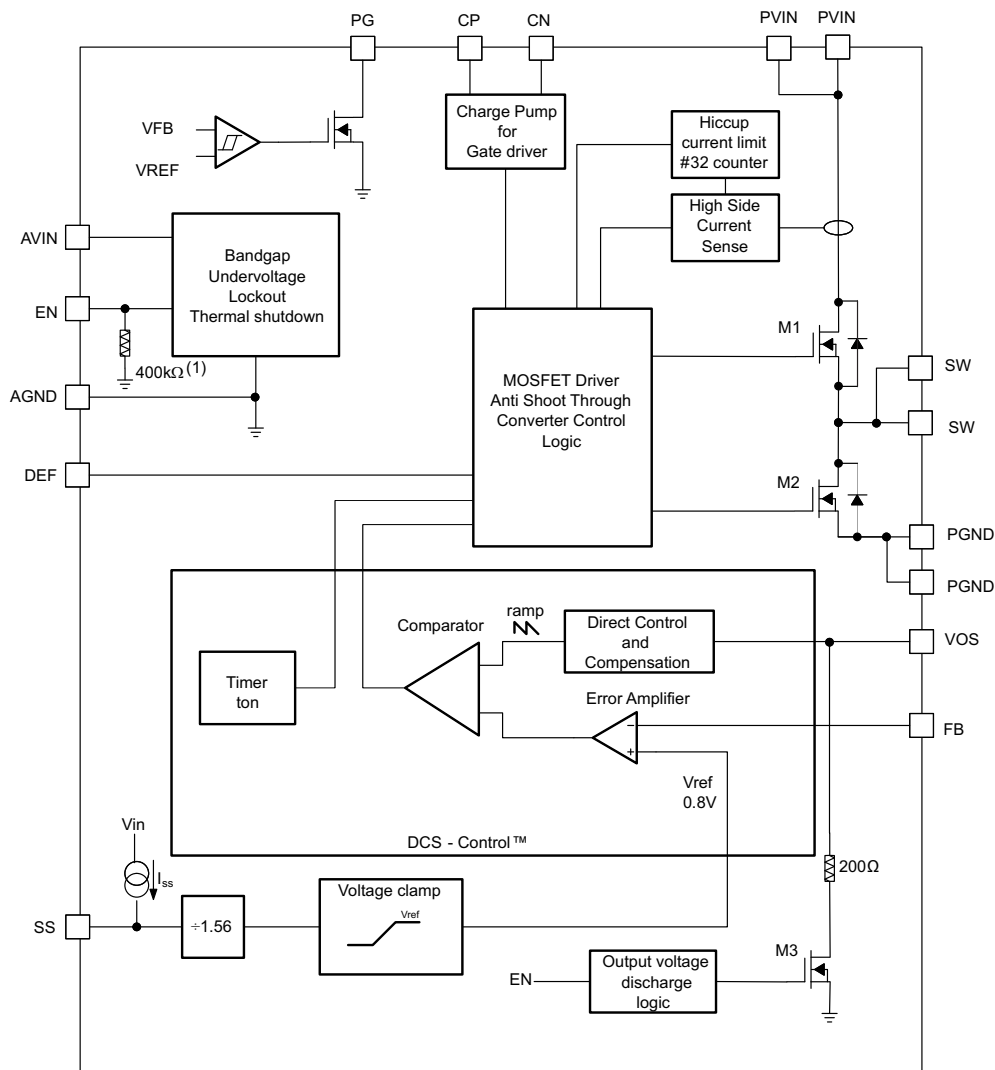
## 7 Detailed Description

### 7.1 Overview

The TLV62090 synchronous switched mode converter is based on DCS-Control™ (direct control with seamless transition into power save mode). This is an advanced regulation topology that combines the advantages of hysteretic and voltage-mode control.

The DCS-Control™ topology operates in pulse width modulation (PWM) mode for medium to heavy load conditions and in power save mode at light load currents. In PWM mode, the converter operates with its nominal switching frequency of 1.4 MHz having a controlled frequency variation over the input voltage range. As the load current decreases, the converter enters power save mode, reducing the switching frequency and minimizing the current consumption to achieve high efficiency over the entire load current range. DCS-Control™ supports both operation modes (PWM and PFM) using a single building block having a seamless transition from PWM to power save mode without effects on the output voltage. The TLV62090 offers excellent DC voltage regulation and load transient regulation, combined with low output voltage ripple, minimizing interference with RF circuits.

### 7.2 Functional Block Diagram



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(1) The resistor is disconnected when EN is high.

## 7.3 Feature Description

### 7.3.1 Enable (EN)

The device is enabled by setting the EN pin to a logic high. Accordingly, shutdown mode is forced if the EN pin is pulled low with a shutdown current of typically 0.6  $\mu\text{A}$ . In shutdown mode, the internal power switches as well as the entire control circuitry are turned off. An internal resistor of 200  $\Omega$  discharges the output through the VOS pin smoothly. An internal pull-down resistor of 400 k $\Omega$  is connected to the EN pin when the EN pin is low. The pull-down resistor is disconnected when the EN pin is high.

### 7.3.2 Softstart (SS) and Hiccup Current Limit During Startup

To minimize inrush current during start up, the device has an adjustable softstart depending on the capacitor value connected to the SS pin. The device charges the softstart capacitor with a constant current of typically 7.5  $\mu\text{A}$ . The feedback voltage follows this voltage with a fraction of 1.56 until the internal reference voltage of 0.8 V is reached. Softstart operation is completed once the voltage at the softstart capacitor has reached typically 1.25 V. The softstart time is calculated using [公式 1](#). The larger the softstart capacitor, the longer the softstart time. The relation between softstart voltage and feedback voltage is estimated using [公式 2](#).

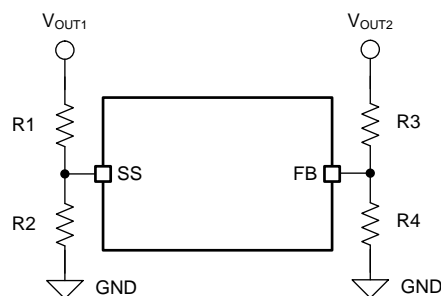
$$t_{\text{SS}} = C_{\text{SS}} \times \frac{1.25\text{V}}{7.5\mu\text{A}} \quad (1)$$

$$V_{\text{FB}} = \frac{V_{\text{SS}}}{1.56} \quad (2)$$

During startup, the switch current limit is reduced to 1/3 (~1.5 A) of its typical current limit of 4.6 A. Once the output voltage exceeds typically 0.6 V, the current limit is released to its nominal value. The device provides a reduced load current of ~1.5 A when the output voltage is below typically 0.6 V. Due to this, a small or no softstart time may trigger the short circuit protection during startup especially for larger output capacitors. This is avoided by using a larger softstart capacitance to extend the softstart time. See [Short Circuit Protection \(Hiccup-Mode\)](#) for details of the reduced current limit during startup. Leaving the softstart pin floating sets the minimum startup time (around 50  $\mu\text{s}$ ).

### 7.3.3 Voltage Tracking (SS)

The SS pin is externally driven by another voltage source to achieve output voltage tracking. The application circuit is shown in [图 9](#). The internal reference voltage follows the voltage at the SS pin with a fraction of 1.56 until the internal reference voltage of 0.8 V is reached. The device achieves ratiometric or coincidental (simultaneous) output tracking, as shown in [图 10](#).



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**图 9. Output Voltage Tracking**

Feature Description (接下页)

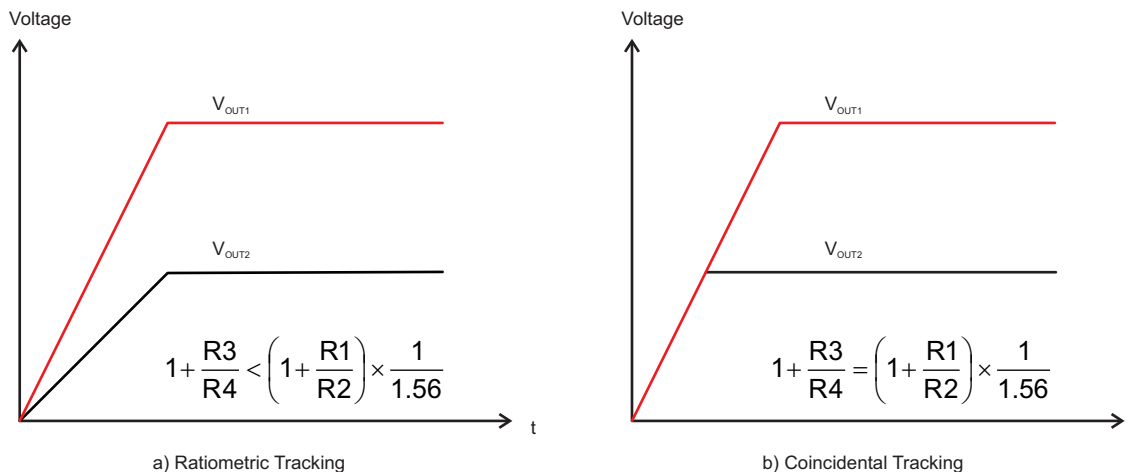


图 10. Voltage Tracking Options

The R2 value should be set properly to achieve accurate voltage tracking by taking 7.5 μA soft startup current into account. 1 kΩ or smaller is a sufficient value for R2.

For decreasing the SS pin voltage, the device doesn't sink current from the output when the device is in power save mode. So the resulting decreases of the output voltage may be slower than the SS pin voltage if the load is light. When driving the SS pin with an external voltage, do not exceed the voltage rating of the SS pin which is 7 V.

7.3.4 Short Circuit Protection (Hiccup-Mode)

The device is protected against hard short circuits to GND and over-current events. This is implemented by a two level short circuit protection. During startup and when the output is shorted to GND, the switch current limit is reduced to 1/3 of its typical current limit of 4.6 A. Once the output voltage exceeds typically 0.6 V, the current limit is released to its nominal value. The full current limit is implemented as a hiccup current limit. Once the internal current limit is triggered 32 times, the device stops switching and starts a new startup sequence after a typical delay time of 66 μS. The device goes through these cycles until the high current condition is released.

7.3.5 Output Discharge Function

To make sure the device starts up under defined conditions, the output gets discharged via the VOS pin with a typical discharge resistor of 200 Ω whenever the device shuts down. This happens when the device is disabled or if thermal shutdown, undervoltage lockout or short circuit hiccup-mode are triggered.

## Feature Description (接下页)

### 7.3.6 Power Good Output (PG)

The power good output is low when the output voltage is below its nominal value. The power good becomes high impedance once the output is within 5% of regulation. The PG pin is an open drain output and is specified to typically sink up to 1 mA. This output requires a pull-up resistor to be monitored properly. The pull-up resistor cannot be connected to any voltage higher than the input voltage of the device. The PG output is low when the device is disabled, in thermal shutdown or UVLO. The PG output can be left floating if unused. 表 1 shows the PG pin logic.

**表 1. Power Good Pin Logic**

Device State		PG Logic Status	
		High Impedance	Low
Enable (EN=High)	$V_{FB} \geq V_{TH\_PG}$	√	
	$V_{FB} \leq V_{TH\_PG}$		√
Shutdown (EN=Low)			√
UVLO	$0.7\text{ V} < V_{IN} \leq V_{UVLO}$		√
Thermal Shutdown	$T_J > T_{SD}$		√
Power Supply Removal	$V_{IN} \leq 0.7\text{ V}$	√	

### 7.3.7 Undervoltage Lockout (UVLO)

To avoid mis-operation of the device at low input voltages, an undervoltage lockout is included. UVLO shuts down the device at input voltages lower than typically 2.2 V with a 200 mV hysteresis.

### 7.3.8 Thermal Shutdown

The device goes into thermal shutdown once the junction temperature exceeds typically 150°C with a 20°C hysteresis.

### 7.3.9 Charge Pump (CP, CN)

The CP and CN pins must attach to an external 10 nF capacitor to complete a charge pump for the gate driver. This capacitor must be rated for the input voltage. It is not recommended to connect any other circuits to the CP or CN pins.

## 7.4 Device Functional Modes

### 7.4.1 PWM Operation

At medium to heavy load currents, the device operates with pulse width modulation (PWM) at a nominal switching frequency of 1.4 MHz. As the load current decreases, the converter enters power save mode operation reducing its switching frequency. The device enters power save mode at the boundary to discontinuous conduction mode (DCM).

### 7.4.2 Power Save Mode Operation

As the load current decreases, the converter enters power save mode operation. During power save mode, the converter operates with reduced switching frequency maintaining high efficiency. Power save mode is based on a fixed on-time architecture following [公式 3](#).

$$\begin{aligned}
 t_{on} &= \frac{V_{OUT}}{V_{IN}} \times 360\text{ns} \times 2 \\
 f &= \frac{2 \times I_{OUT}}{t_{on}^2 \left( 1 + \frac{V_{IN} - V_{OUT}}{V_{OUT}} \right) \times \frac{V_{IN} - V_{OUT}}{L}}
 \end{aligned}
 \tag{3}$$

In power save mode, the output voltage rises slightly above the nominal output voltage in PWM mode, as shown in [图 15](#). This effect is reduced by increasing the output capacitance or the inductor value. This effect is also reduced by programming the output voltage of the TLV62090 lower than the target value. As an example, if the target output voltage is 3.3 V, then the TLV62090 can be programmed to 3.3 V - 0.8%. As a result the output voltage accuracy is now -2.2% to +2.2% instead of -1.4% to 3%. The output voltage accuracy in pulse frequency modulation (PFM) operation is reflected in the electrical specification table and given for a 22-μF output capacitor.

### 7.4.3 Low Dropout Operation (100% Duty Cycle)

The device offers a low input to output voltage difference by entering 100% duty cycle mode. In this mode, the high-side MOSFET switch is constantly turned on. This is particularly useful in battery powered applications to achieve longest operation time by taking full advantage of the whole battery voltage range. The minimum input voltage where the output voltage falls below its nominal regulation value is given by:

$$V_{IN(\min)} = V_{OUT} + I_{OUT} \times ( R_{DS(on)} + R_L )
 \tag{4}$$

Where

$R_{DS(on)}$  = High side FET on-resistance

$R_L$  = DC resistance of the inductor

## 8 Application and Implementation

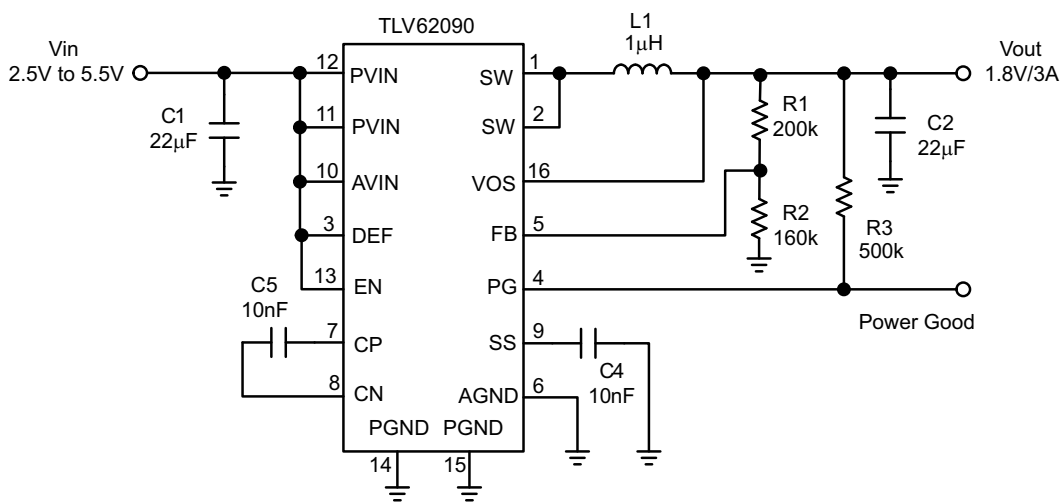
### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TLV62090 is a 3-A high frequency synchronous step-down converter optimized for small solution size, high efficiency and suitable for battery powered applications.

### 8.2 Typical Application



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图 11. TLV62090 Typical Application Circuit

#### 8.2.1 Design Requirements

The design guideline provides a component selection to operate the device within the recommended operating conditions.

For the typical application example, the following input parameters are used. See 表 2.

表 2. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUES
Input Voltage Range	2.5 V to 5.5 V
Output Voltage	1.8 V
Transient Response	±5% VOUT
Input Voltage Ripple	400 mV
Output Voltage Ripple	30 mV
Output current rating	3 A
Operating frequency	1.4 MHz

表 3 shows the list of components for the Application Characteristic Curves.

**表 3. List of Components**

REFERENCE	DESCRIPTION	MANUFACTURER
TLV62090	High efficiency step-down converter	Texas Instruments
L1	Inductor: 1 $\mu$ H	Coilcraft XFL4020-102
C1	Ceramic capacitor: 22 $\mu$ F	(6.3V, X5R, 0805)
C2	Ceramic capacitor: 22 $\mu$ F	(6.3V, X5R, 0805)
C4, C5	Ceramic capacitor, 10 nF	Standard
R1, R2, R3	Resistor	Standard

## 8.2.2 Detailed Design Procedure

### 8.2.2.1 Custom Design with WEBENCH® Tools

[Click here](#) to create a custom design using the TLV62090 device with the WEBENCH® Power Designer.

1. Start by entering your  $V_{IN}$ ,  $V_{OUT}$ , and  $I_{OUT}$  requirements.
2. Optimize your design for key parameters like efficiency, footprint and cost using the optimizer dial and compare this design with other possible solutions from Texas Instruments.
3. The WEBENCH Power Designer provides you with a customized schematic along with a list of materials with real time pricing and component availability.
4. In most cases, you will also be able to:
  - Run electrical simulations to see important waveforms and circuit performance
  - Run thermal simulations to understand the thermal performance of your board
  - Export your customized schematic and layout into popular CAD formats
  - Print PDF reports for the design, and share your design with colleagues
5. Get more information about WEBENCH tools at [www.ti.com/WEBENCH](http://www.ti.com/WEBENCH).

The first step is the selection of the output filter components. To simplify this process, [表 4](#) outlines possible inductor and capacitor value combinations.

**表 4. Output Filter Selection**

INDUCTOR VALUE [ $\mu$ H] <sup>(1)</sup>	OUTPUT CAPACITOR VALUE [ $\mu$ F] <sup>(2)</sup>				
	10	22	47	100	150
0.47		√	√	√	√
1.0	√	√ <sup>(3)</sup>	√	√	√
2.2	√	√	√	√	√
3.3					

- (1) Inductor tolerance and current de-rating is anticipated. The effective inductance can vary by +20% and –30%.
- (2) Capacitance tolerance and bias voltage de-rating is anticipated. The effective capacitance can vary by +20% and –50%.
- (3) Typical application configuration. Other check mark indicates alternative filter combinations

### 8.2.2.2 Inductor Selection

The inductor selection is affected by several parameters like inductor ripple current, output voltage ripple, transition point into power save mode, and efficiency. See 表 5 for typical inductors.

**表 5. Inductor Selection**

INDUCTOR VALUE	COMPONENT SUPPLIER	SIZE (LxWxH mm)	Isat/DCR (max)
0.6 μH	Coilcraft XAL4012-601	4 x 4 x 2.1	7.9A/10.5 mΩ
1 μH	Coilcraft XAL4020-102	4 x 4 x 2.1	6.7A/14.6 mΩ
1 μH	Coilcraft XFL4020-102	4 x 4 x 2.1	4.5 A/11.9 mΩ
0.47 μH	TOKO DFE252012CR47	2.5 x 2 x 1.2	3.7A/39 mΩ
1 μH	TOKO DFE252012C1R0	2.5 x 2 x 1.2	3.0A/59 mΩ
0.68 μH	TOKO DFE322512CR68	3.2 x 2.5 x 1.2	3.5A/35 mΩ
1 μH	TOKO DFE322512C1R0	3.2 x 2.5 x 1.2	3.1A/45 mΩ

In addition, the inductor has to be rated for the appropriate saturation current and DC resistance (DCR). 公式 5 and 公式 6 calculate the maximum inductor current under static load conditions. The formula takes the converter efficiency into account. The converter efficiency can be taken from the data sheet graphs or 80% can be used as a conservative approach. The calculation must be done for the maximum input voltage where the peak switch current is highest.

$$\Delta I_L = \frac{V_{OUT}}{\eta} \times \left( 1 - \frac{V_{OUT}}{V_{IN} \times \eta} \right) \div (f \times L) \quad (5)$$

$$I_{PEAK} = I_{OUT} + \frac{\Delta I_L}{2} \quad (6)$$

where

$f$  = Converter switching frequency (typically 1.4 MHz)

$L$  = Selected inductor value

$\eta$  = Estimated converter efficiency (use the number from the efficiency curves or 0.80 as a conservative assumption)

Calculating the maximum inductor current using the actual operating conditions gives the minimum saturation current. A margin of about 20% should be added to cover for load transients during operation.

### 8.2.2.3 Input and Output Capacitor Selection

For best output and input voltage filtering, low ESR (X5R or X7R) ceramic capacitors are recommended. The input capacitor minimizes input voltage ripple, suppresses input voltage spikes and provides a stable system rail for the device. A 22-μF or larger input capacitor is recommended. The output capacitor value can range from 10 μF up to 150 μF and beyond. Load transient testing and measuring the bode plot are good ways to verify stability with larger capacitor values.

The recommended typical output capacitor value is 22 μF (nominal) and can vary over a wide range as outline in the output filter selection table. For output voltages above 1.8 V, noise can cause duty cycle jitter. This does not degrade device performance. Using an output capacitor of 2 x 22 μF (nominal) for output voltages >1.8 V avoids duty cycle jitter.

Ceramic capacitor have a DC-Bias effect, which has a strong influence on the final effective capacitance. Choose the right capacitor carefully in combination with considering its package size and voltage rating.



### 8.2.2.4 Setting the Output Voltage

The output voltage is set by an external resistor divider according to the following equations:

$$V_{OUT} = V_{FB} \times \left(1 + \frac{R1}{R2}\right) = 0.8 \text{ V} \times \left(1 + \frac{R1}{R2}\right) \quad (7)$$

$$R2 = \frac{V_{FB}}{I_{FB}} = \frac{0.8 \text{ V}}{5 \mu\text{A}} \approx 160 \text{ k}\Omega \quad (8)$$

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{FB}} - 1\right) = R2 \times \left(\frac{V_{OUT}}{0.8\text{V}} - 1\right) \quad (9)$$

When sizing R2, in order to achieve low quiescent current and acceptable noise sensitivity, use a minimum of 5  $\mu\text{A}$  for the feedback current  $I_{FB}$ . Larger currents through R2 improve noise sensitivity and output voltage accuracy. A feed forward capacitor is not required for proper operation.

8.2.3 Application Curves

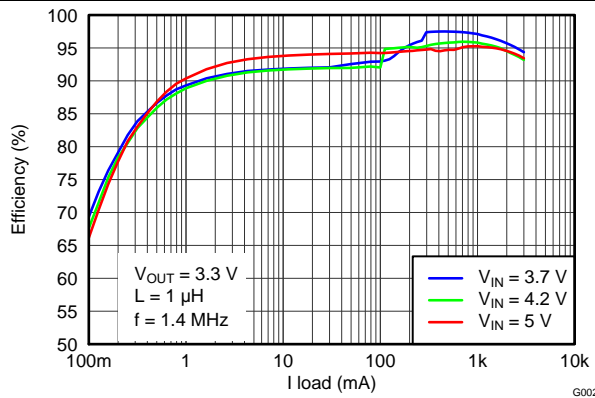


图 12. Efficiency vs Load Current

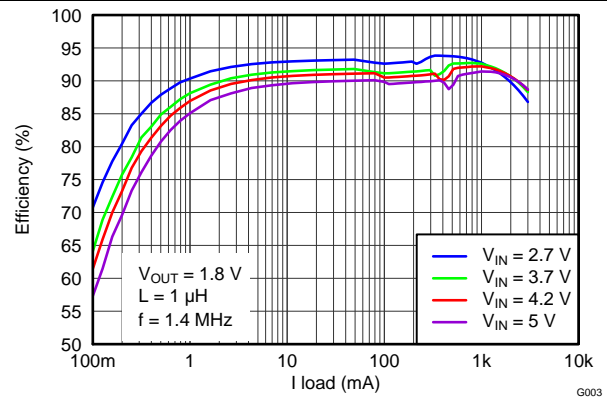


图 13. Efficiency vs Load Current

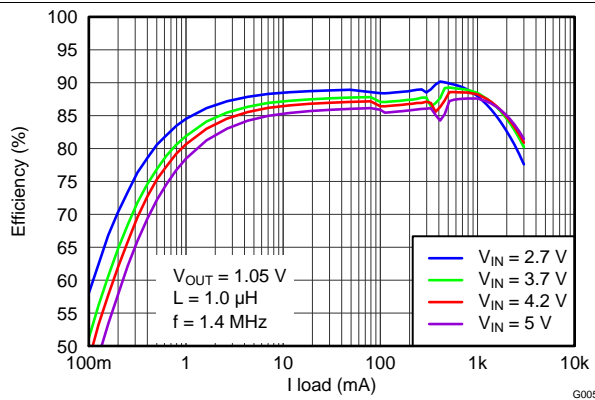


图 14. Efficiency vs Load Current

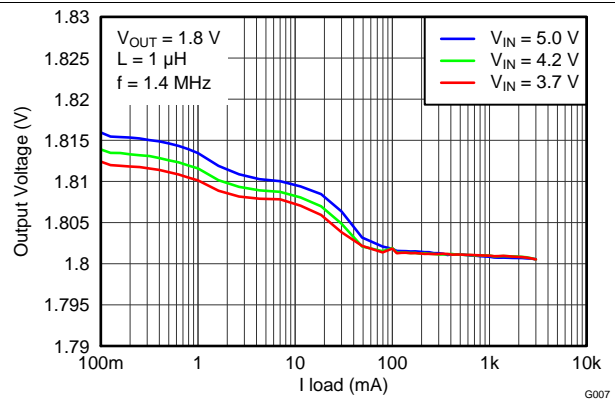


图 15. Output Voltage vs Load Current

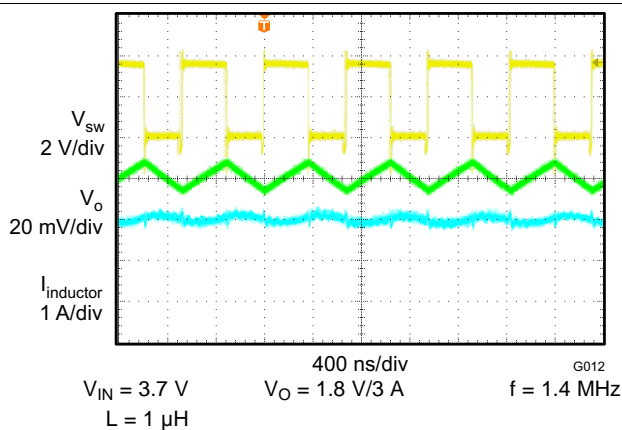


图 16. PWM Operation

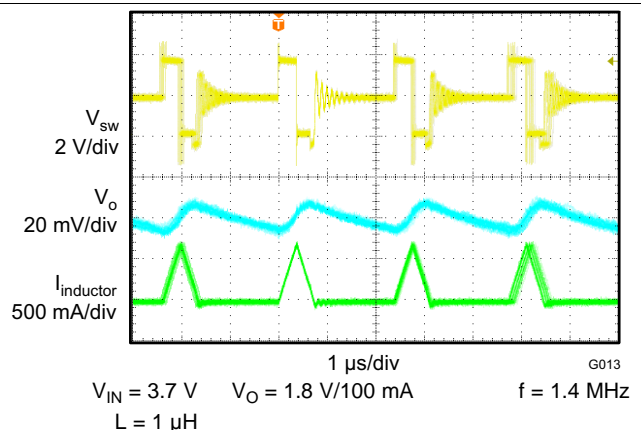


图 17. PFM Operation

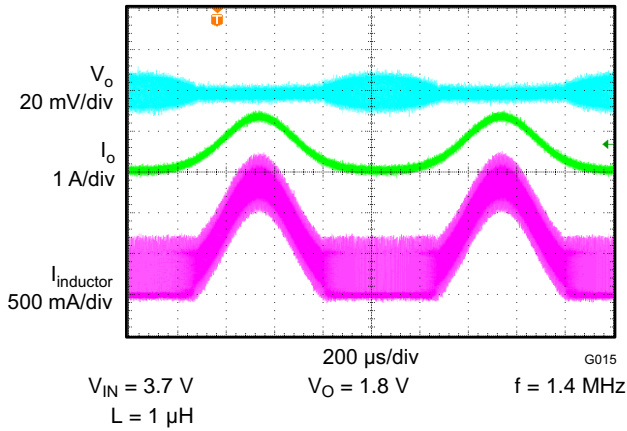


图 18. Load Sweep, 0 to 1.5 A

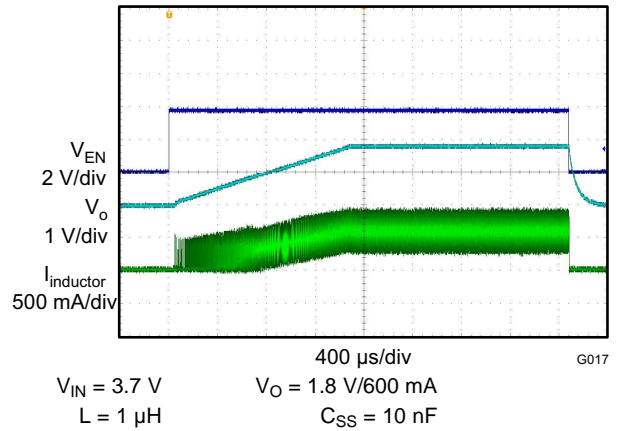


图 19. Start-Up

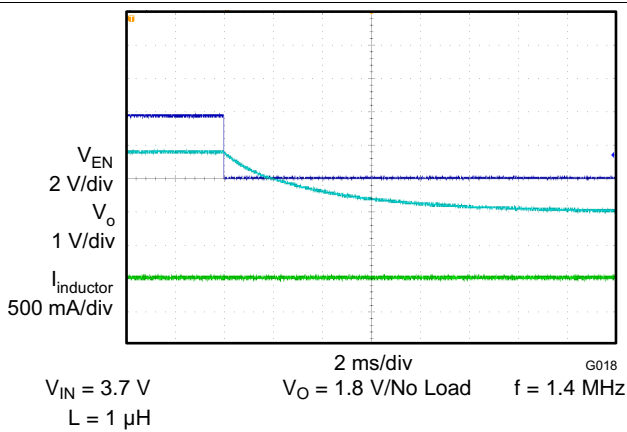


图 20. Shutdown

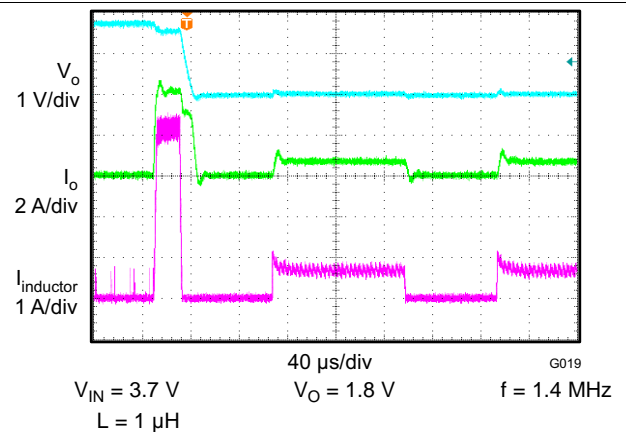


图 21. Hiccup Short Circuit Protection

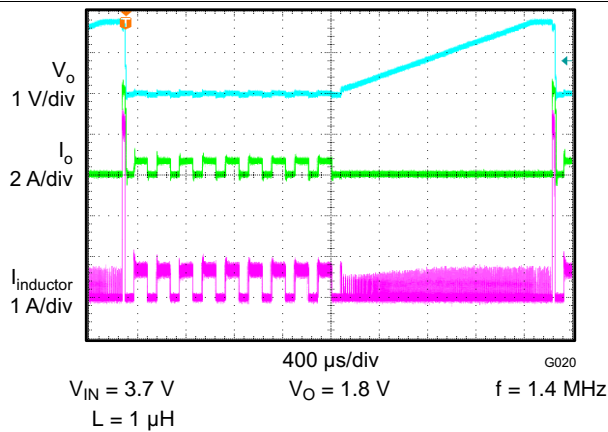


图 22. Hiccup Short Circuit Protection

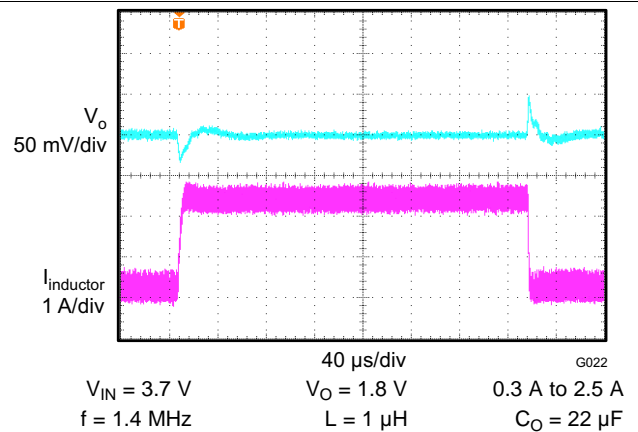
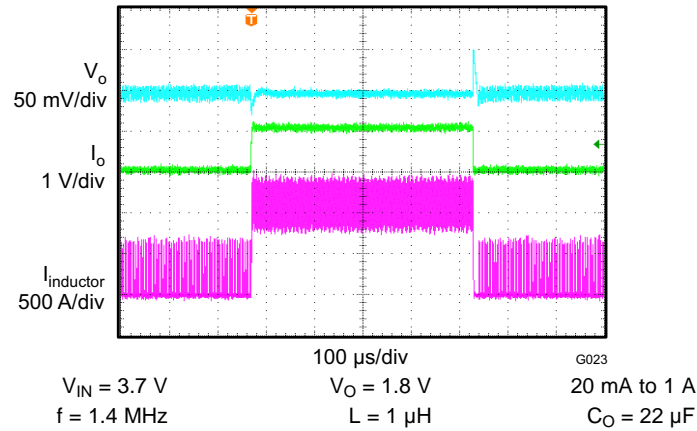


图 23. Load Transient Response


**图 24. Load Transient Response**

## 9 Power Supply Recommendations

The TLV62090 device has no special requirements for its input power supply. The input power supply's output current needs to be rated according to the supply voltage, output voltage and output current of the TLV62090.

## 10 Layout

### 10.1 Layout Guideline

- It is recommended to place the input capacitor as close as possible to the IC pins PVIN and PGND.
- The VOS connection is noise sensitive and needs to be routed short and direct to the output terminal of the inductor.
- The exposed thermal pad of the package, analog ground (pin 6) and power ground (pin 14, 15) should have a single point connection at the exposed thermal pad of the package. This minimizes switch node jitter.
- The charge pump capacitor connected to CP and CN should be placed close to the IC to minimize coupling of switching waveforms into other traces and circuits.
- See [图 25](#) and the evaluation module User Guide (SLVU670) for an example of component placement, routing and thermal design.

### 10.2 Layout Example

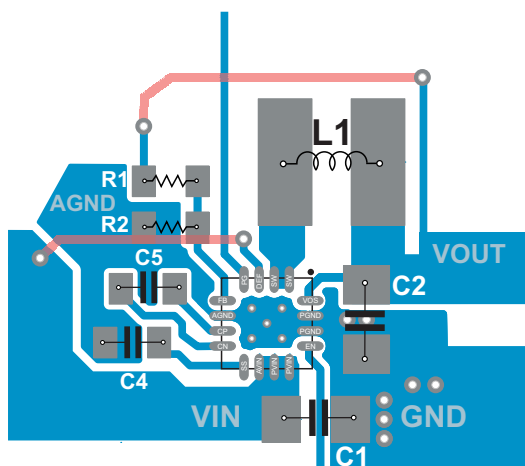


图 25. Recommended Layout

## 11 器件和文档支持

### 11.1 器件支持

#### 11.1.1 使用 WEBENCH® 工具定制设计方案

请单击[此处](#)，借助 并使用 TLV62090 器件定制设计方案 WEBENCH®Power Designer 并使用 TLV62090 器件定制设计方案。

1. 首先输入您的  $V_{IN}$ 、 $V_{OUT}$  和  $I_{OUT}$  要求。
2. 使用优化器拨盘可优化效率、封装和成本等关键设计参数并将您的设计与德州仪器 (TI) 的其他可行解决方案进行比较。
3. WEBENCH Power Designer 提供一份定制原理图以及罗列实时价格和组件可用性的物料清单。
4. 在多数情况下，您还可以：
  - 运行电气仿真，观察重要波形以及电路性能
  - 运行热性能仿真，了解电路板热性能
  - 将定制原理图和布局方案导出至常用 CAD 格式
  - 打印设计方案的 PDF 报告并与同事共享
5. 有关 WEBENCH 工具的详细信息，请访问 [www.ti.com/WEBENCH](http://www.ti.com/WEBENCH)。

### 11.2 文档支持

#### 11.2.1 Third-Party Products Disclaimer

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### 11.4 社区资源

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### 11.6 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

## 11.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。



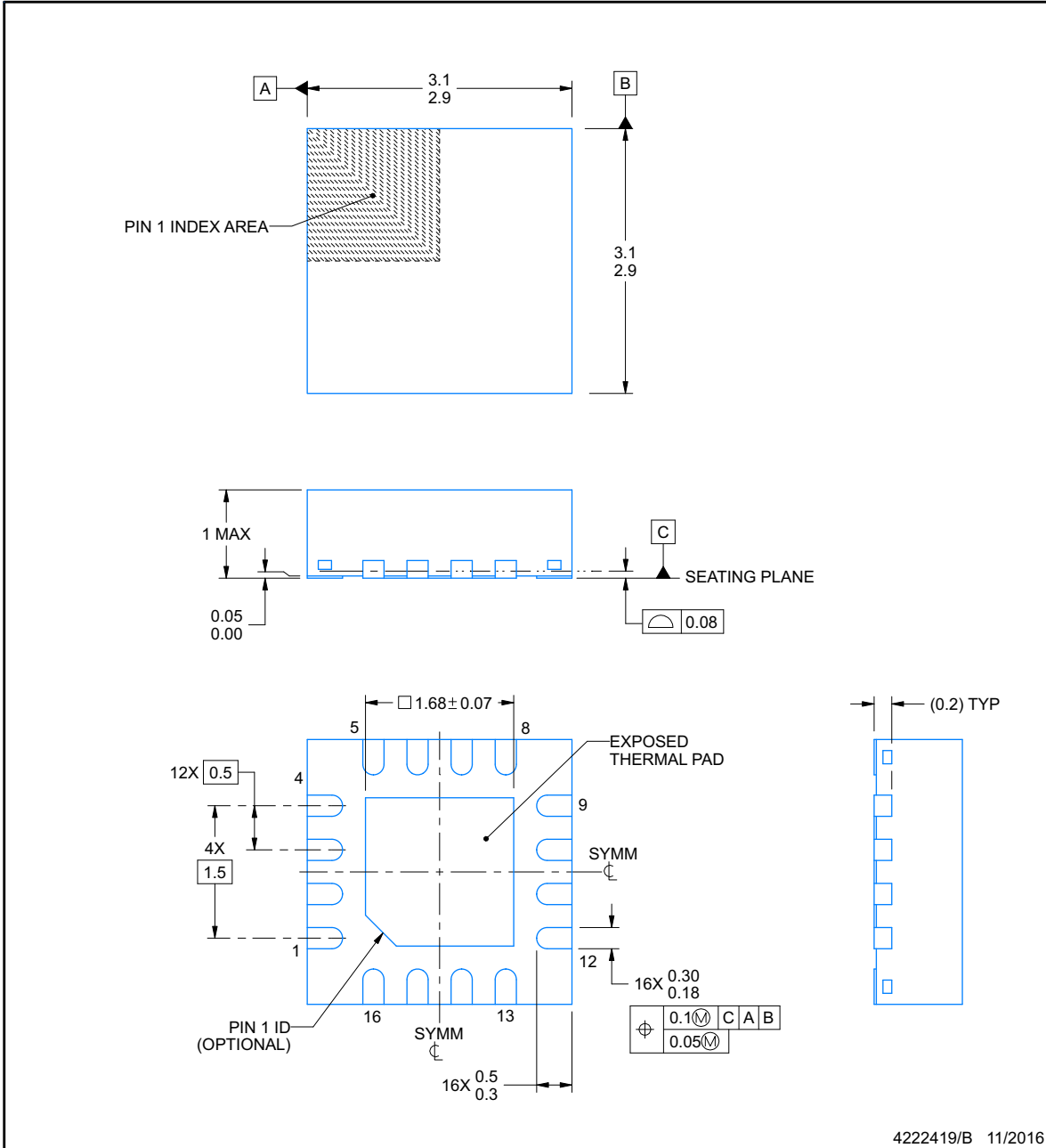


PACKAGE OUTLINE

RGT0016C

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES:

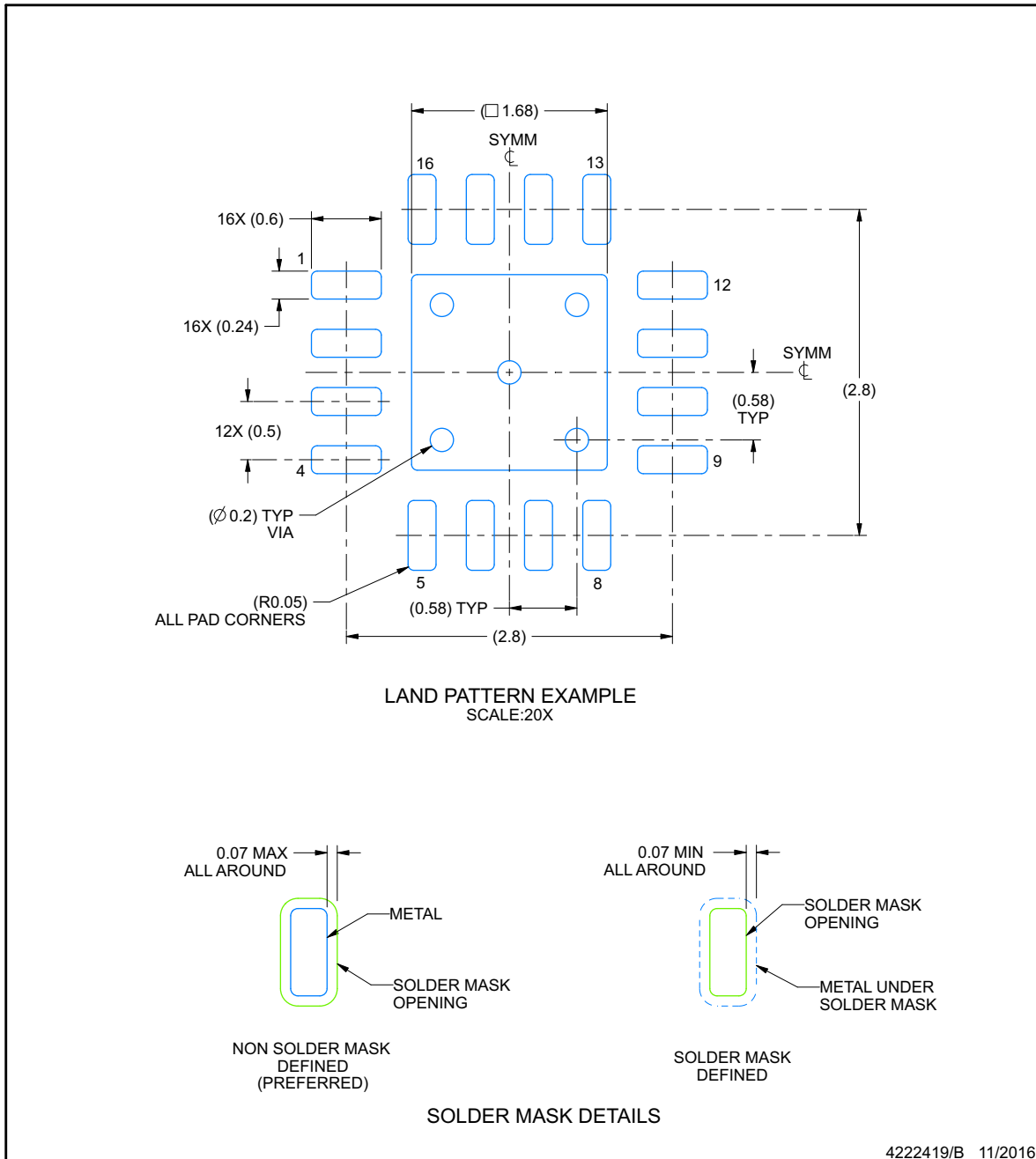
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

RGT0016C

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

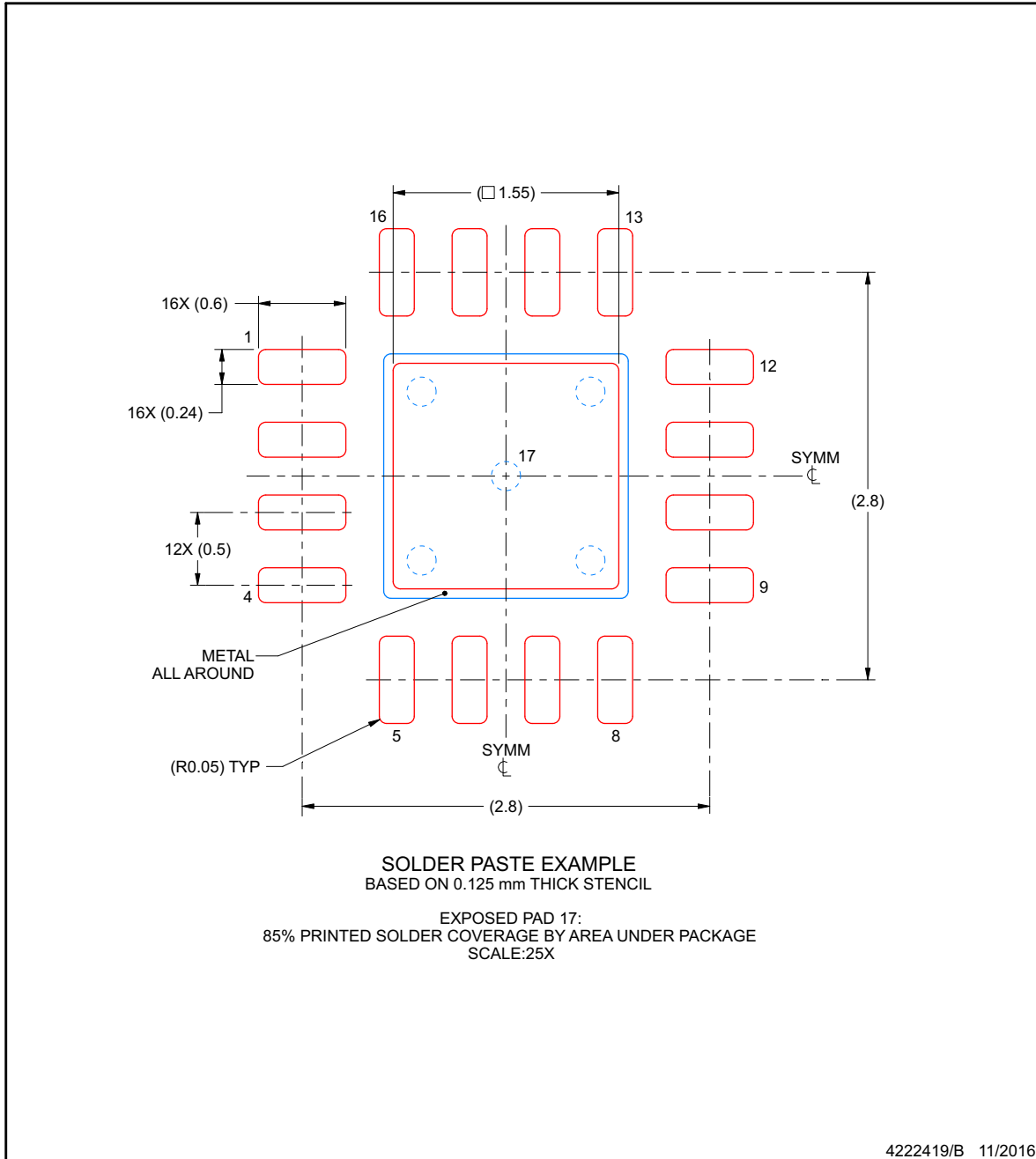
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGT0016C

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLV62090RGTR	ACTIVE	VQFN	RGT	16	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SBV	<a href="#">Samples</a>
TLV62090RGTT	ACTIVE	VQFN	RGT	16	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SBV	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV62090RGTR	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TLV62090RGTT	VQFN	RGT	16	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV62090RGTR	VQFN	RGT	16	3000	346.0	346.0	33.0
TLV62090RGTT	VQFN	RGT	16	250	210.0	185.0	35.0

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